



US00D408139S

United States Patent [19]

Fan et al.

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[54] **WAFER POD**

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[**] Term: **14 Years**

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Primary Examiner—Philip S. Hyder
Attorney, Agent, or Firm—W. Wayne Liauh

[21] Appl. No.: **29/077,908**

[22] Filed: **Aug. 12, 1997**

[57] CLAIM

The ornamental design for a wafer pod, as shown and described.

[51] **LOC (6) CL** **03-01**

[52] **U.S. Cl.** **D3/273; D3/269**

[58] **Field of Search** **D3/273, 269, 302;**
D9/420, 423, 424; 206/444, 445, 454, 455,
503, 508

DESCRIPTION

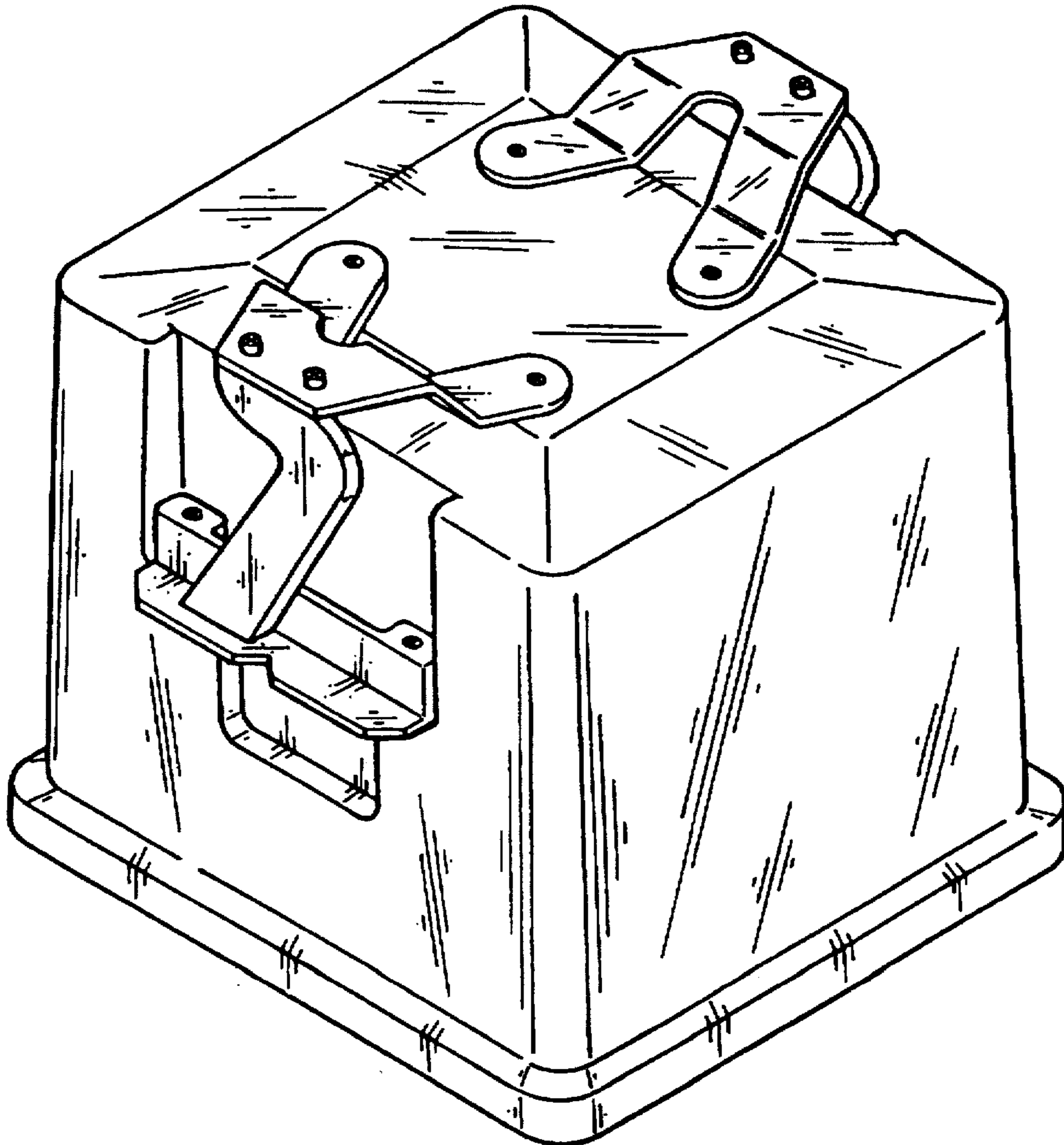
FIG. 1 is a perspective view of a wafer pod showing the preferred embodiment of my new design;
 FIG. 2 is a front elevational view of the wafer pod;
 FIG. 3 is a rear elevational view of the wafer pod;
 FIG. 4 is a left elevational side view of the wafer pod;
 FIG. 5 is a right elevational side view of the wafer pod;
 FIG. 6 is a top plan view of the wafer pod; and,
 FIG. 7 is a bottom plan view of the wafer pod.

[56] References Cited

U.S. PATENT DOCUMENTS

D. 344,891 3/1994 Dressen D9/424
 D. 376,688 12/1996 Gallagher et al. D3/273
 D. 387,903 12/1997 Jacoby et al. D3/269

1 Claim, 4 Drawing Sheets



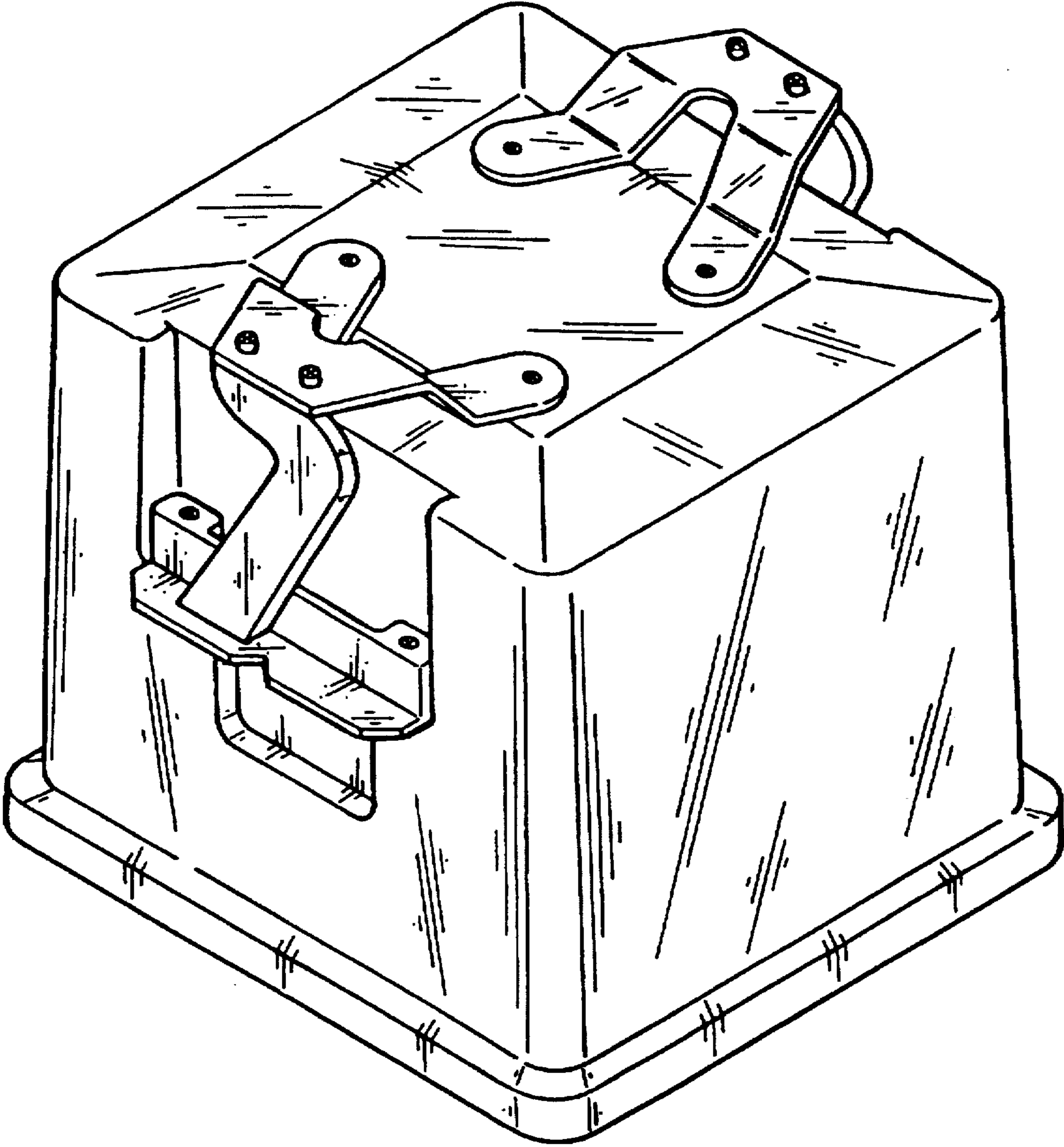


Fig . 1

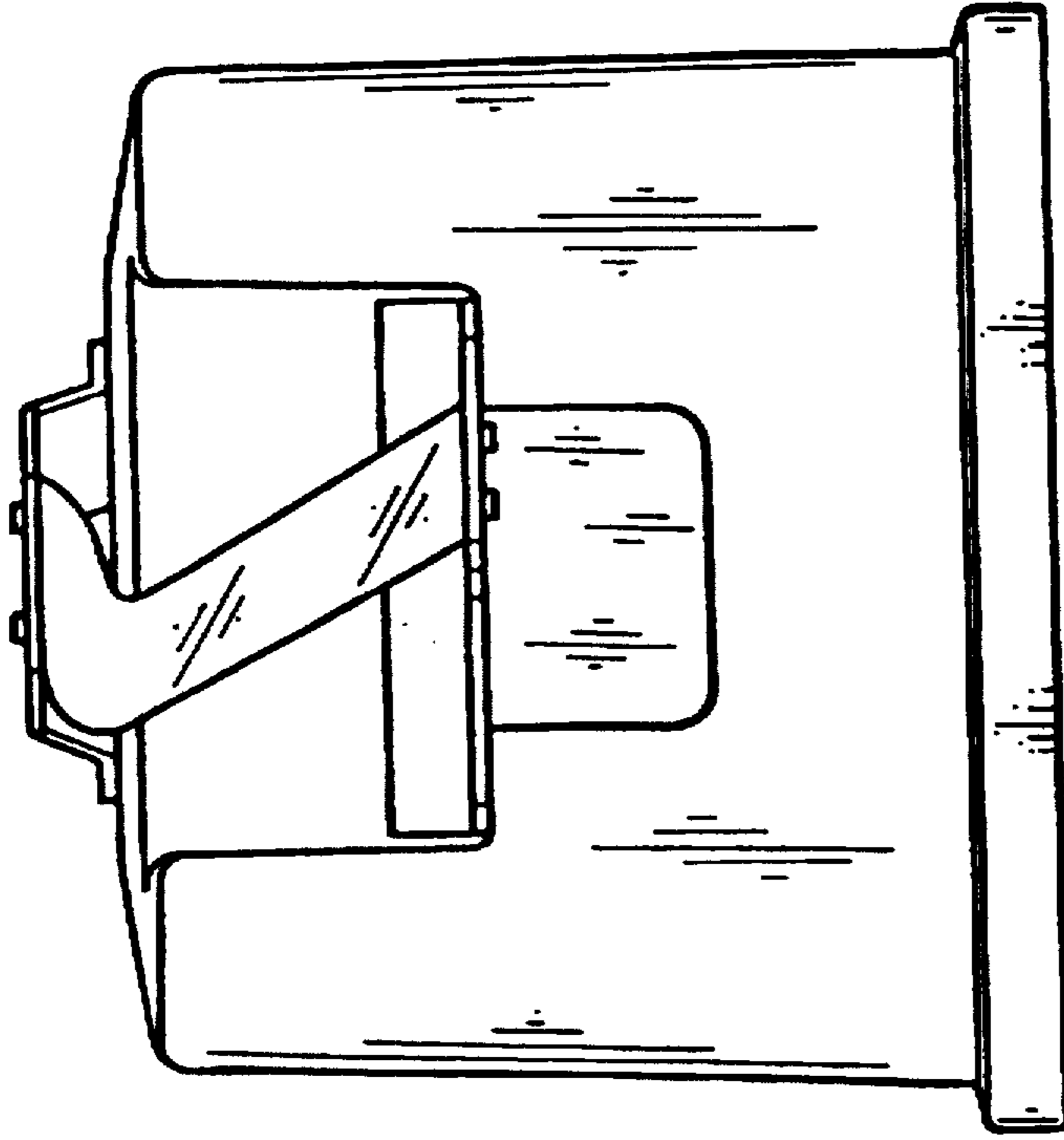


Fig . 3

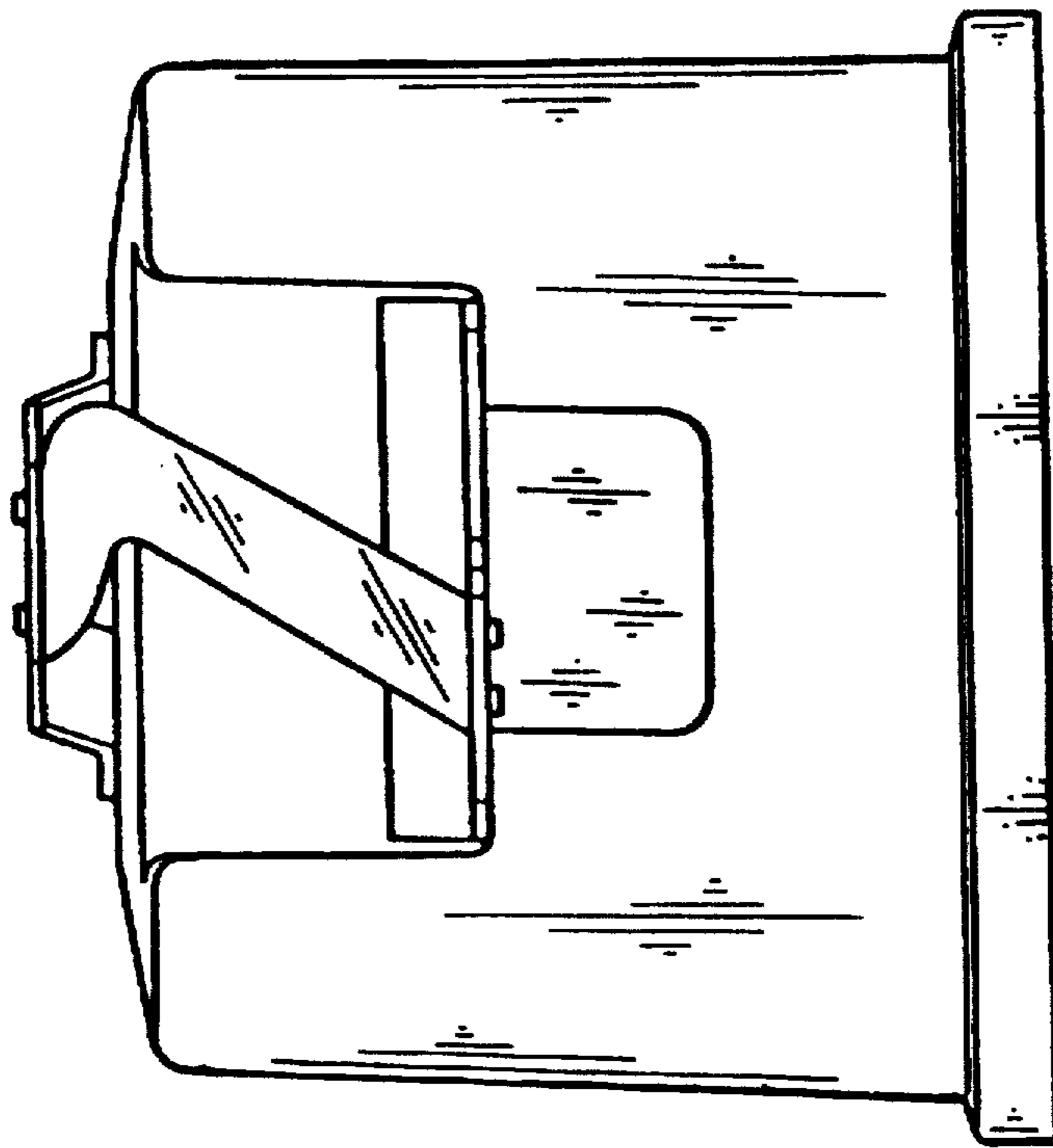


Fig . 2

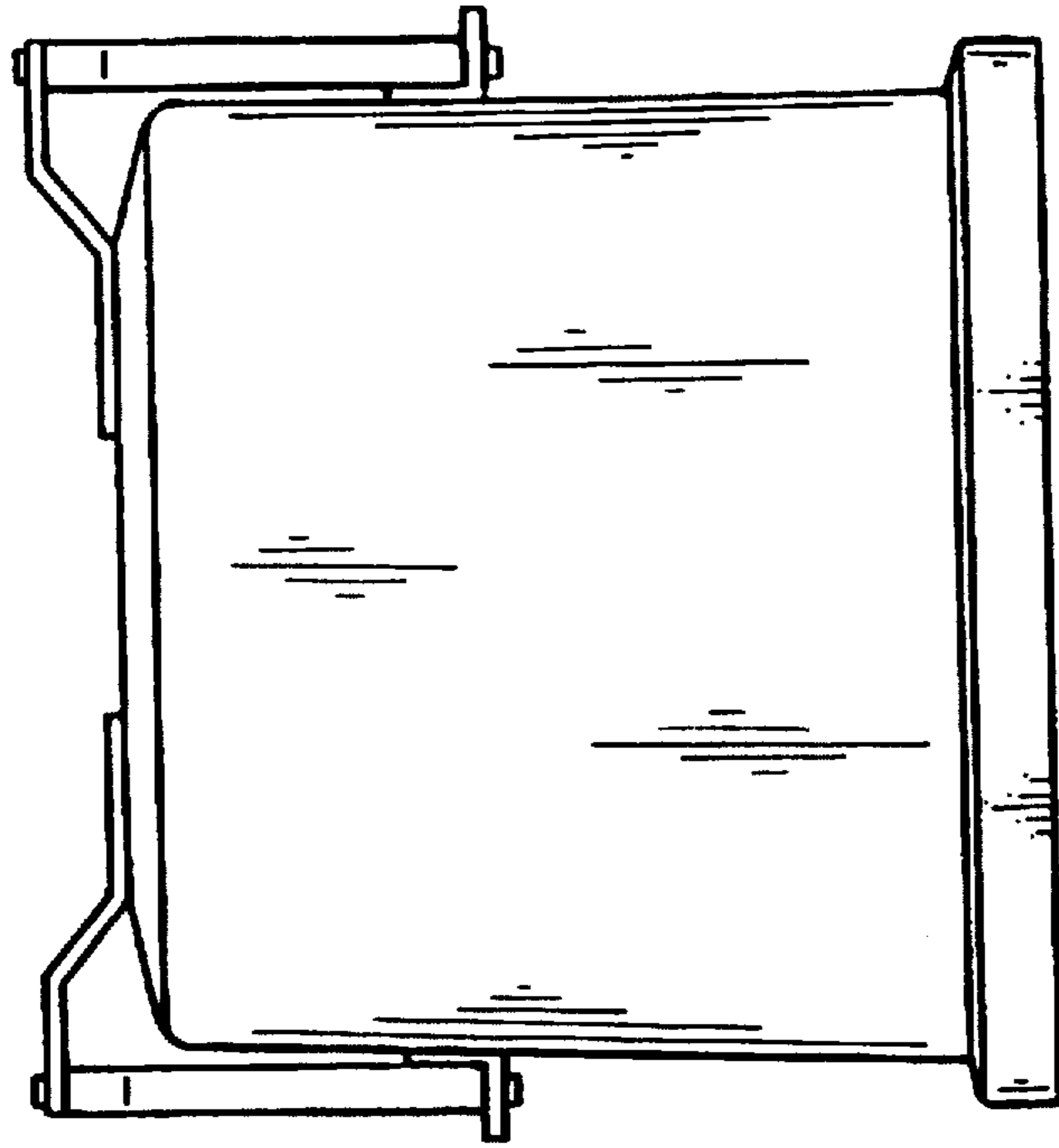


Fig . 5

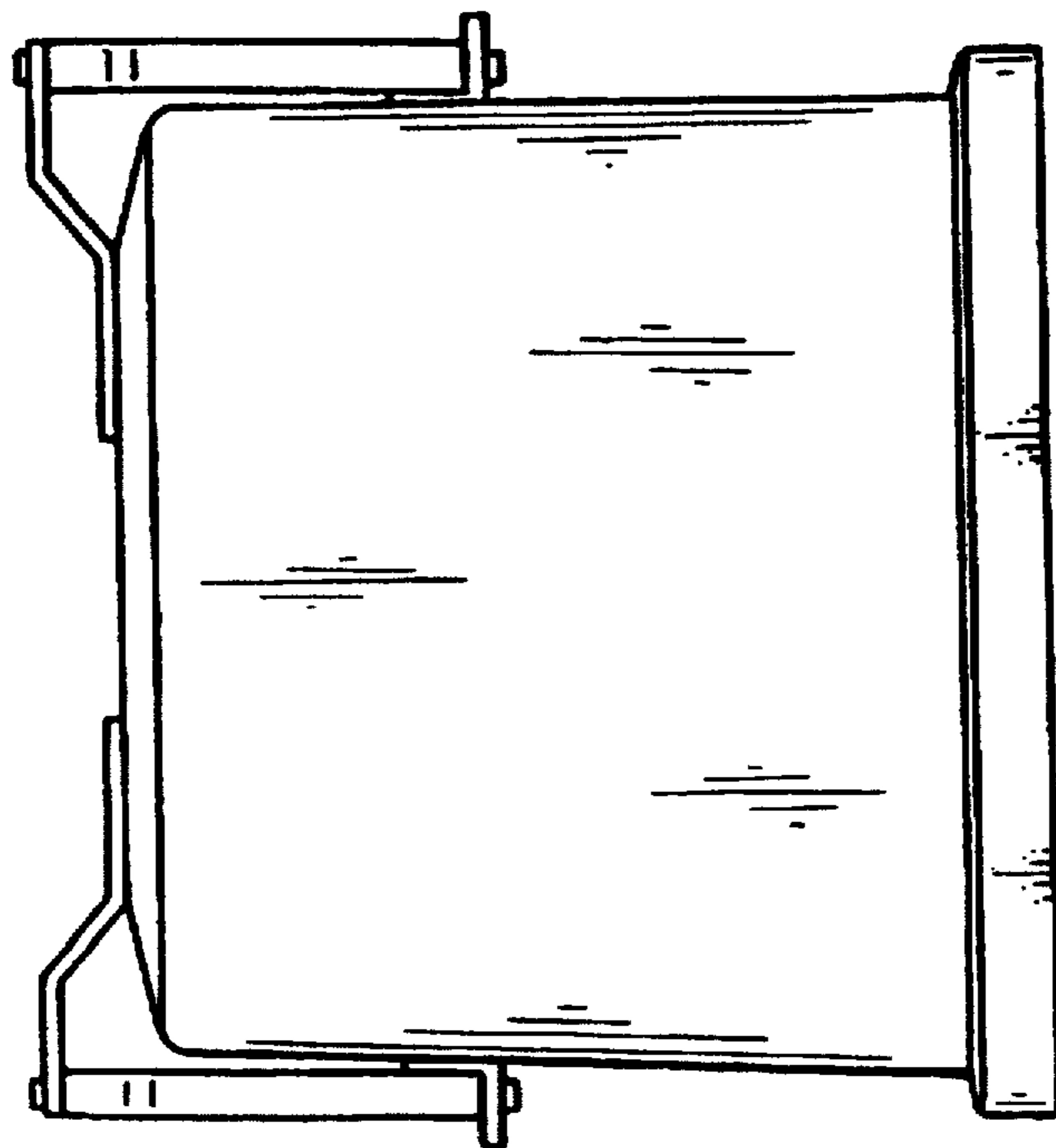


Fig . 4

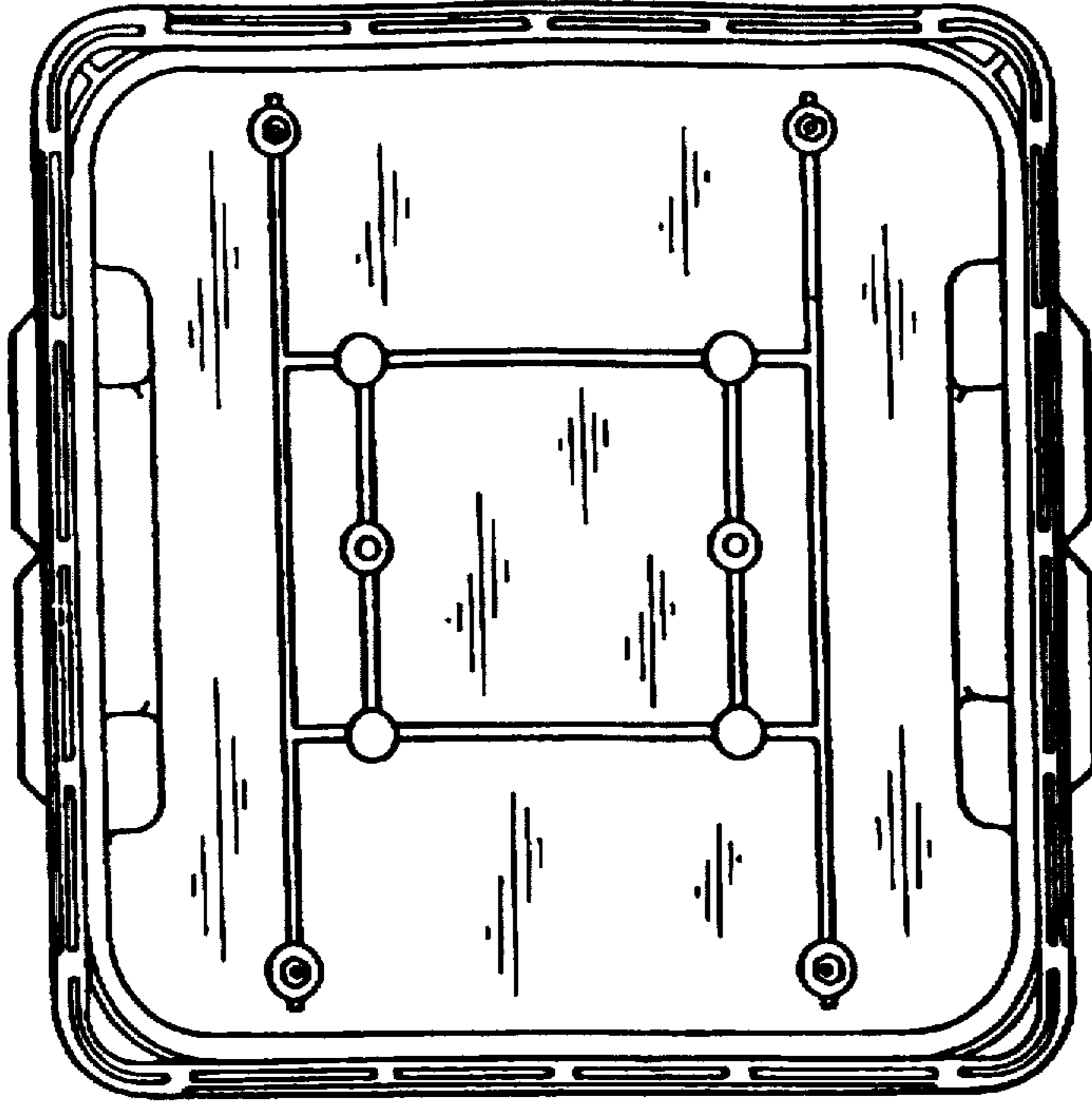


Fig. 7

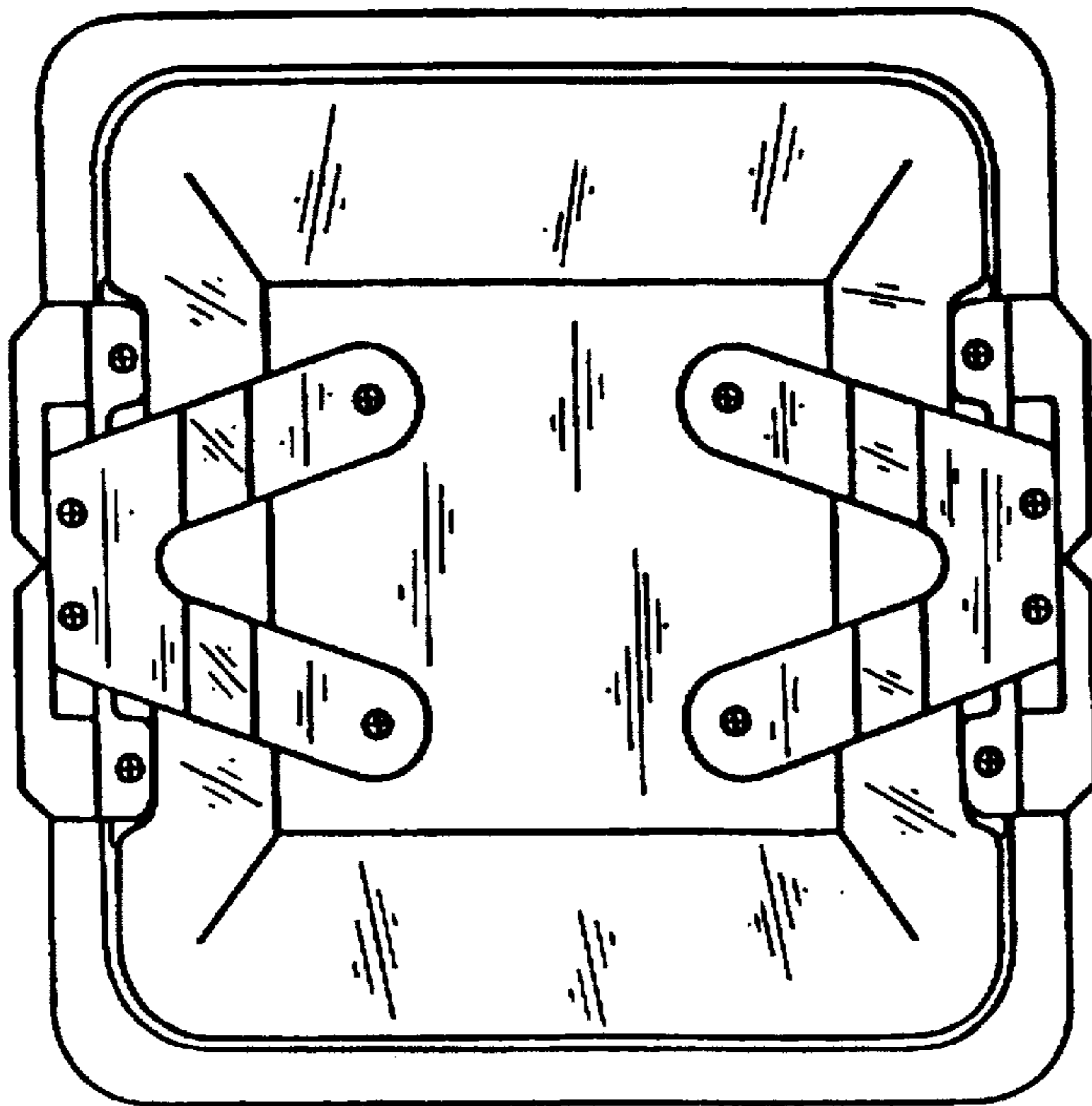


Fig. 6